

**Features**

- Ultra Low Forward Voltage Drop
- Superior Reverse Avalanche Capability
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **“Green” Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

- Case: DFN1006-2
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Dot
- Terminals: Finish - NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.001 grams

**Maximum Ratings** @ T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	100	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	70	V
Average Rectified Output Current (See Figure 1)	I <sub>O</sub>	250	mA
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	5	A
Maximum Thermal Resistance Thermal Resistance, Junction to Ambient (Note 2) T <sub>A</sub> = 25°C Thermal Resistance, Junction to Ambient (Note 3) T <sub>A</sub> = 25°C	R <sub>θJA</sub> R <sub>θJA</sub>	270 235	°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 4)	V <sub>(BR)R</sub>	100	-	-	V	I <sub>R</sub> = 1mA
Forward Voltage Drop	V <sub>F</sub>	-	0.67 0.76 0.60	0.72 0.80 0.65	V	I <sub>F</sub> = 100mA, T <sub>j</sub> = 25°C I <sub>F</sub> = 200mA, T <sub>j</sub> = 25°C I <sub>F</sub> = 200mA, T <sub>j</sub> = 125°C
Leakage Current (Note 4)	I <sub>R</sub>	-	0.04 6	1.0 50	μA	V <sub>R</sub> = 75V, T <sub>j</sub> = 25°C V <sub>R</sub> = 75V, T <sub>j</sub> = 85°C

- Notes:
1. RoHS revision 13.2.2003. High temperature solder exemption applied, see *EU Directive Annex Note 7*.
  2. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>
  3. Polyimide PCB, 2 oz. Copper, minimum recommended pad layout per <http://www.diodes.com/datasheets/ap02001.pdf>
  4. Short duration pulse test used to minimize self-heating effect.

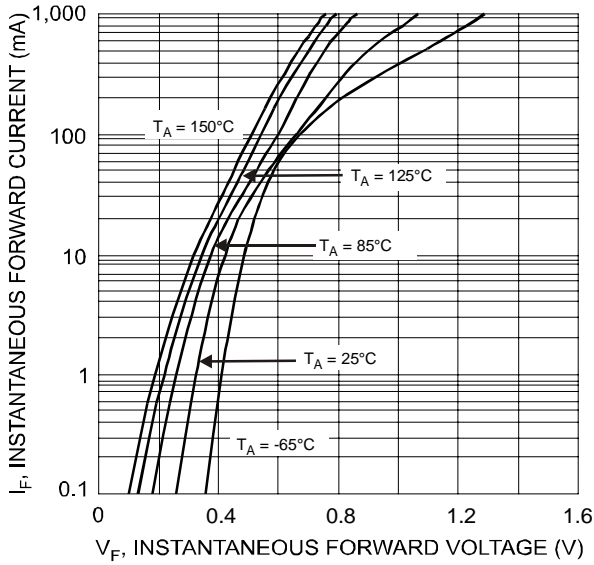


Fig. 1 Typical Forward Characteristics

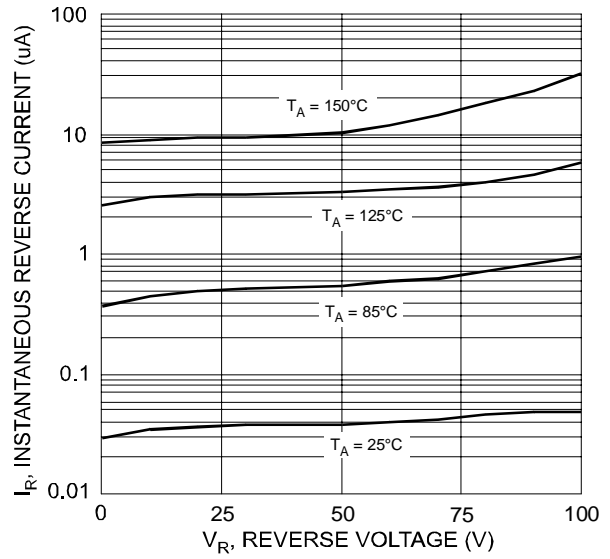


Fig. 2 Typical Reverse Characteristics

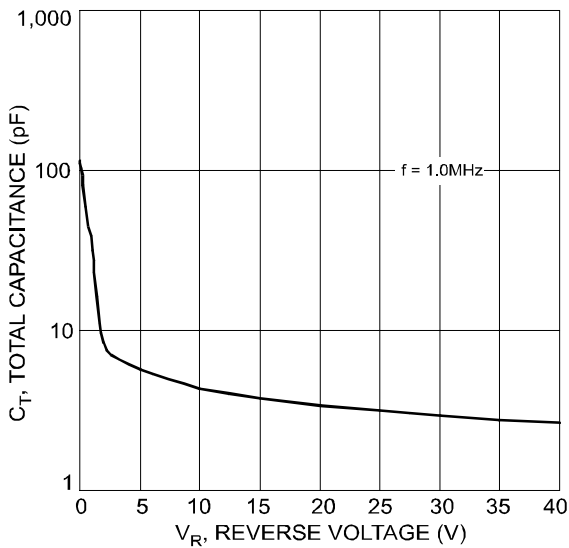


Fig. 3 Typical Total Capacitance

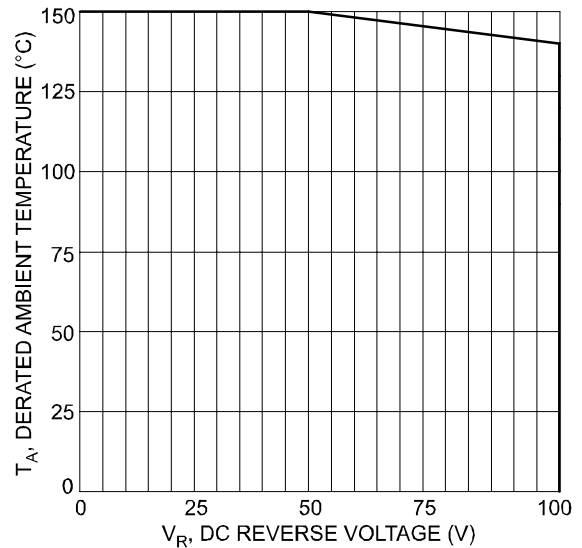


Fig. 4 Operating Temperature Derating

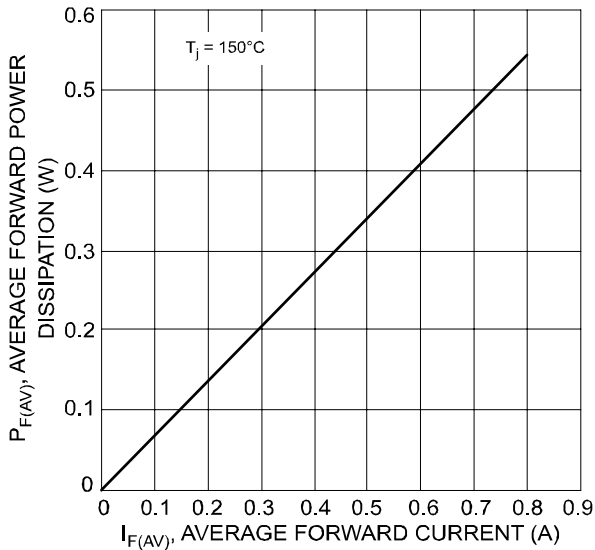


Fig. 5 Forward Power Dissipation

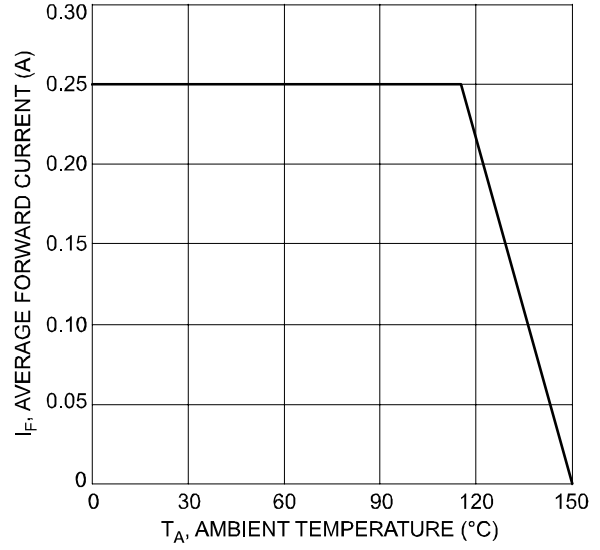
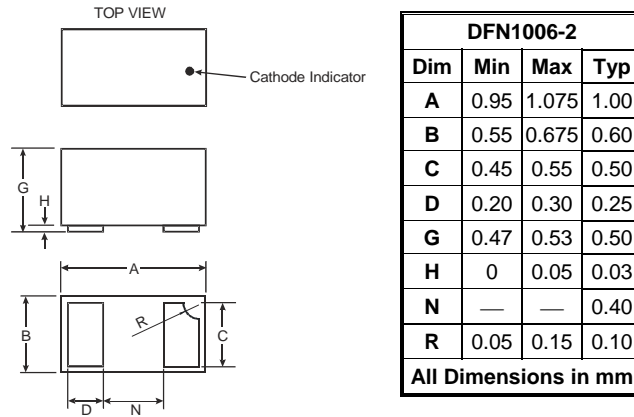


Fig. 6 DC Forward Current Derating

NEW PRODUCT

## Package Outline Drawing

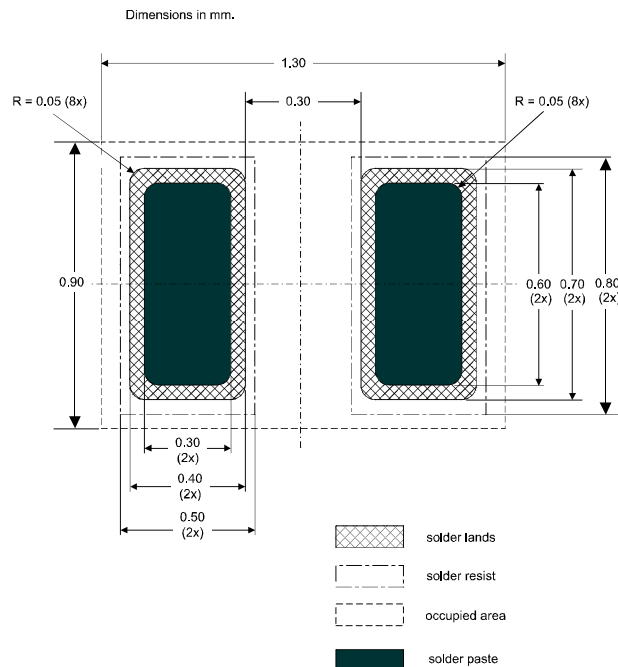


## Marking, Polarity, Weight & Ordering Information

SBR02U100LP	Case Style (DFN1006-2)		Marking	Weight
			 	0.001g (approx.)

Ordering Information	Date Code
SBR02U100LP-7 3000/Tape & Reel	<u>2</u> A, 2A = Product Type Marking Code Dot Denotes Cathode Side

## Suggested Pad Layout



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